

## CLAIMS:

1. An etching method in which two or more disk-shaped members immersed into an etching solution are held in a state where plate surfaces of the members face each other, and etching is conducted while rotating the members,  
wherein non-rotating member is disposed between the members.
2. The etching method according to claim 1, wherein the non-rotating member has a substantially disk shape.
3. The etching method according to claim 1 or 2,  
wherein the surface area of the non-rotating member is 95-105% of the surface area of the members.
4. The etching method according to any one of claims 1 to 3, wherein the members are semiconductor wafers.
5. An etching apparatus comprising:  
an etching chamber filled with an etching solution; and  
a plurality of rods rotatably supported in contact with outer peripheries of a plurality of disk-shaped members to rotatably hold the members in a state where the plate surfaces of the members face each other,  
wherein a non-rotating member is arranged in a position between the members held by the member holding means.
6. The etching apparatus according to claim 5, further comprising support columns fixed parallel to the rods, wherein the non-rotating member is fixed to the support columns.

7. The etching apparatus according to claim 5 or 6, wherein the non-rotating member has a substantially disk shape.
8. The etching apparatus according to any one of claims 5 to 7 wherein the surface area of the non-rotating member is 95-105% of the surface area of the members.
9. A non-rotating member in an etching apparatus comprising:  
an etching chamber filled with an etching solution; and  
a plurality of rods rotatably supported in contact with outer peripheries of a plurality of disk-shaped members to rotatably hold the members in a state where the plate surfaces of the members face each other,  
wherein the non-rotating member is supported by the rods in place of the members, and  
a protruding section for preventing the rotation of the non-rotating member is provided on the outer periphery thereof.
10. The non-rotating member according to claim 9, wherein the non-rotating member has a substantially disk shape.
11. The non-rotating member according to claim 9 or 10, wherein the surface area of the non-rotating member is 95-105% of the surface area of the members.
12. The non-rotating member according to any one of claims 9 to 11, wherein the non-rotating member is made from polypropylene.
13. A method for manufacturing semiconductor wafers comprising a step of etching two or more wafers immersed into an etching solution, while holding the wafers so that the plate surfaces thereof face each other, the etching being preformed while rotating the wafers,  
wherein a member that changes flow of the etching solution between each adjacent pair of the wafers is arranged.